

Title (en)
METHOD FOR PRODUCING A METALIZED COMPONENT, CORRESPONDING COMPONENT, AND A SUBSTRATE FOR SUPPORTING THE COMPONENT DURING METALIZATION

Title (de)
VERFAHREN ZUR HERSTELLUNG EINES METALLISIERTEN BAUTEILS, BAUTEIL SOWIE EINEN TRÄGER ZUR AUFLAGE DES BAUTEILS BEI DER METALLISIERUNG

Title (fr)
PROCÉDÉ DE RÉALISATION D'UN COMPOSANT MÉTALLISÉ, COMPOSANT ET SUPPORT SUR LEQUEL LE COMPOSANT REPOSE LORS DE LA MÉTALLISATION

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Application
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Abstract (en)
[origin: WO2008128947A1] When components having ceramic bases are provided with a metalized structure on at least two opposite and/or juxtaposed faces at the same time, it is very difficult to stack said bases. According to the invention, the metal in the form of pastes, films or sheets provided for metalization is applied to the surfaces of the ceramic base to be provided with a metalized structure. Before the metal is joined to the ceramic material, the at least one component is placed on a substrate and a stack is formed, the substrate being previously provided with a separation layer on a face of the substrate on those surfaces intended for support on the at least one component. The at least one component is lifted off the substrate after metalization.

IPC 8 full level
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